



June 2014

FDMA430NZ

Single N-Channel 2.5V Specified PowerTrench[®] MOSFET

30V, 5.0A, 40mΩ

General Description

This Single N-Channel MOSFET has been designed using Fairchild Semiconductor's advanced Power Trench process to optimize the $R_{DS(on)}$ @ $V_{GS}=2.5V$ on special MicroFET leadframe.

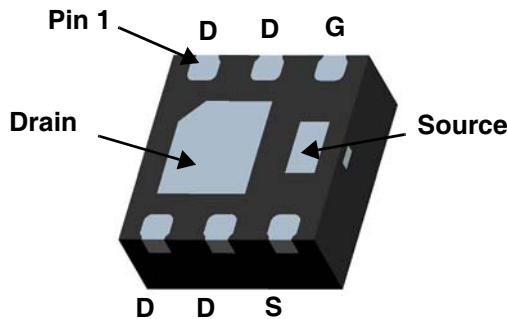
Applications

- Li-Ion Battery Pack

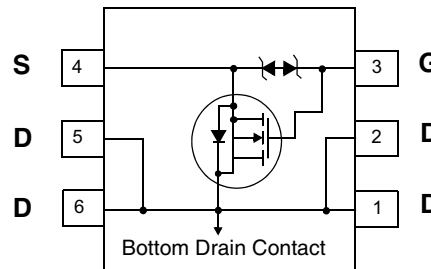


Features

- $R_{DS(on)} = 40m\Omega$ @ $V_{GS} = 4.5 V, I_D = 5.0A$
- $R_{DS(on)} = 50m\Omega$ @ $V_{GS} = 2.5 V, I_D = 4.5A$
- Low Profile-0.8mm maximum-in the new package MicroFET 2x2 mm
- HBM ESD protection level > 2.5kV typical (Note 3)
- Free from halogenated compounds and antimony oxides
- RoHS Compliant



MicroFET 2X2 (Bottom View)



Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

Symbol	Parameter	Rated	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Drain Current -Continuous (Note 1a) -Pulsed	5.0	A
		20	
P_D	Power dissipation (Steady State) (Note 1a) (Note 1b)	2.4	W
		0.9	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	52	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1b)	145	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
430	FDMA430NZ	7"	8 mm	3000 units

FDMA430NZ Single N-Channel 2.5V Specified PowerTrench[®] MOSFET

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
--------	-----------	-----------------	-----	-----	-----	-------

Off Characteristics

B_{VDSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	30			V
$\frac{\Delta B_{VDSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to 25°C		25.2		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24V, V_{GS} = 0V$,			1	μA
I_{GSS}	Gate-Body Leakage,	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 10	μA

On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.6	0.81	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to 25°C		-3.2		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5V, I_D = 5.0A$		23.6	40	m Ω
		$V_{GS} = 4.0V, I_D = 5.0A$		23.9	41	
		$V_{GS} = 3.1V, I_D = 4.5A$		25.4	43	
		$V_{GS} = 2.5V, I_D = 4.5A$		27.6	50	
		$V_{GS} = 4.5V, I_D = 5.0A$, $T_J = 150^\circ\text{C}$		37.0	61	
g_{FS}	Forward Transconductance	$V_{DS} = 5V, I_D = 5.0A$		25.6		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 10V, V_{GS} = 0V$, $f = 1.0\text{MHz}$		600	800	pF
C_{oss}	Output Capacitance			110	150	pF
C_{rss}	Reverse Transfer Capacitance			75	115	pF
R_G	Gate Resistance	$f = 1.0\text{MHz}$		3.5		Ω

Switching Characteristics (Note 2)

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 10V, I_D = 1A$ $V_{GS} = 4.5V, R_{GEN} = 6\Omega$		8.3	17	ns
t_r	Turn-On Rise Time			7.1	15	ns
$t_{d(off)}$	Turn-Off Delay Time			18.1	37	ns
t_f	Turn-Off Fall Time			6.0	12	ns
Q_g	Total Gate Charge	$V_{DS} = 10V, I_D = 5.0A$, $V_{GS} = 4.5V$		7.3	11	nC
Q_{gs}	Gate-Source Charge			0.8	2	nC
Q_{gd}	Gate-Drain Charge			1.9	3	nC

Drain-Source Diode Characteristics and Maximum Ratings

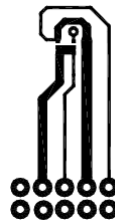
I_S	Maximum Continuous Drain-Source Diode Forward Current			2.0	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 2.0A$	0.69	1.2	V
t_{rr}	Diode Reverse Recovery Time	$I_F = 5.0A$,		17	ns
Q_{rr}	Diode Reverse Recovery Charge	$di/dt = 100A/\mu s$		5	nC

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.



a. 52 $^\circ\text{C/W}$ when mounted on a 1 in² pad of 2 oz copper.



b. 145 $^\circ\text{C/W}$ when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%

3. The diode connected between the gate and the source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

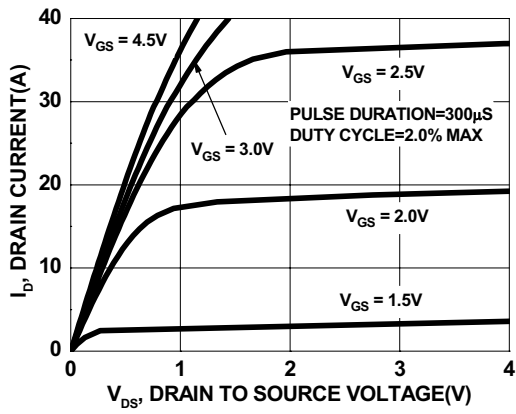


Figure 1. On Region Characteristics

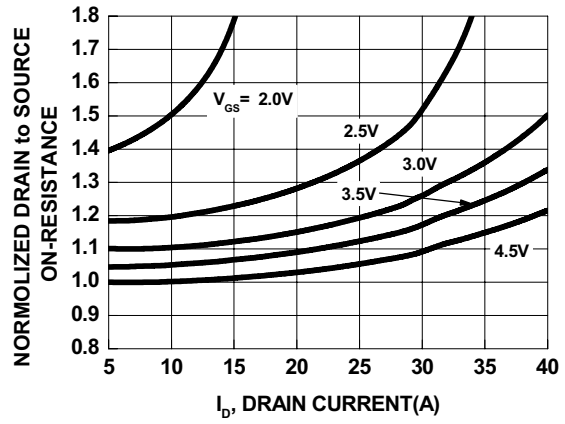


Figure 2. On-Resistance vs Drain Current and Gate Voltage

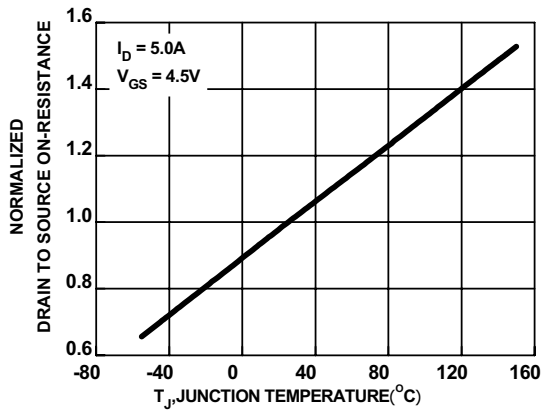


Figure 3. Normalized On Resistance vs Junction Temperature

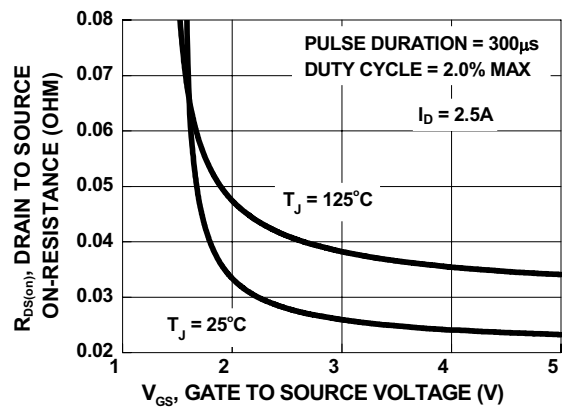


Figure 4. On-Resistance vs Gate to Source Voltage

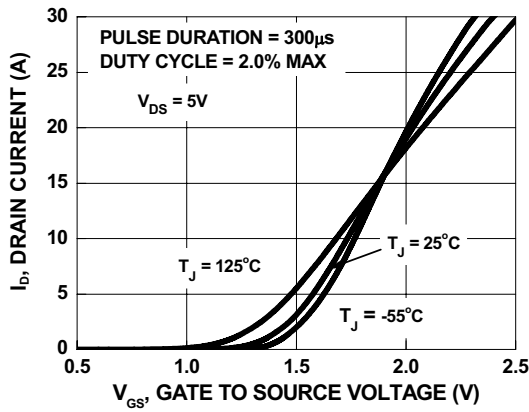


Figure 5. Transfer Characteristics

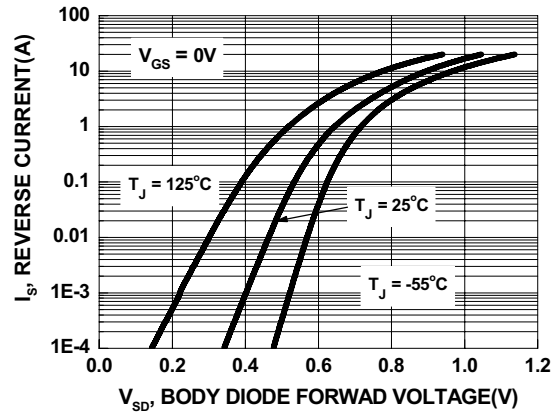


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

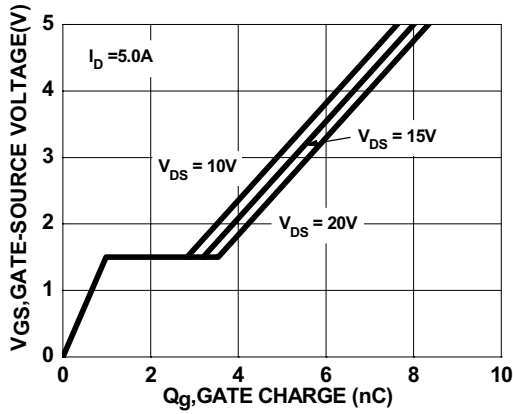


Figure 7. Gate Charge Characteristics

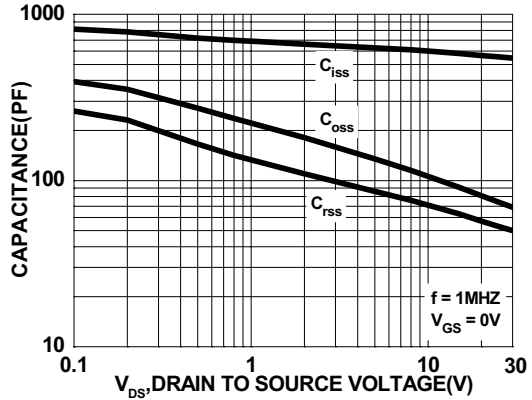


Figure 8. Capacitance vs Drain to Source Voltage

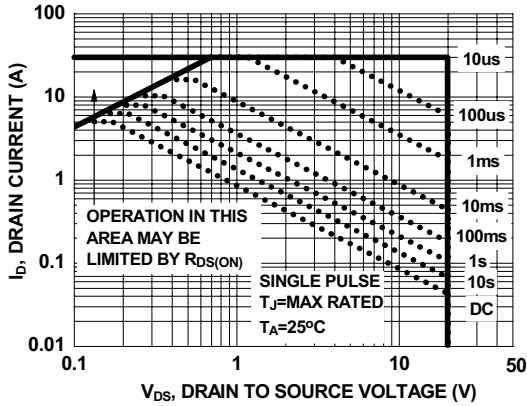


Figure 9. Safe Operating Area

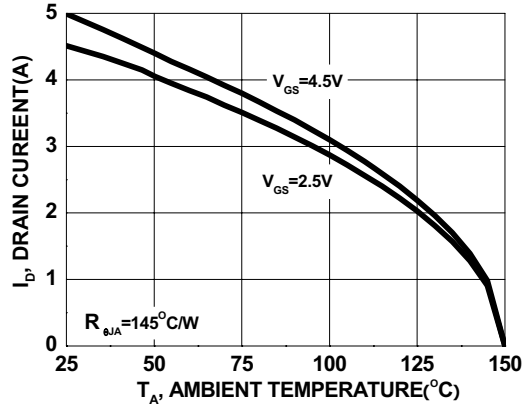


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

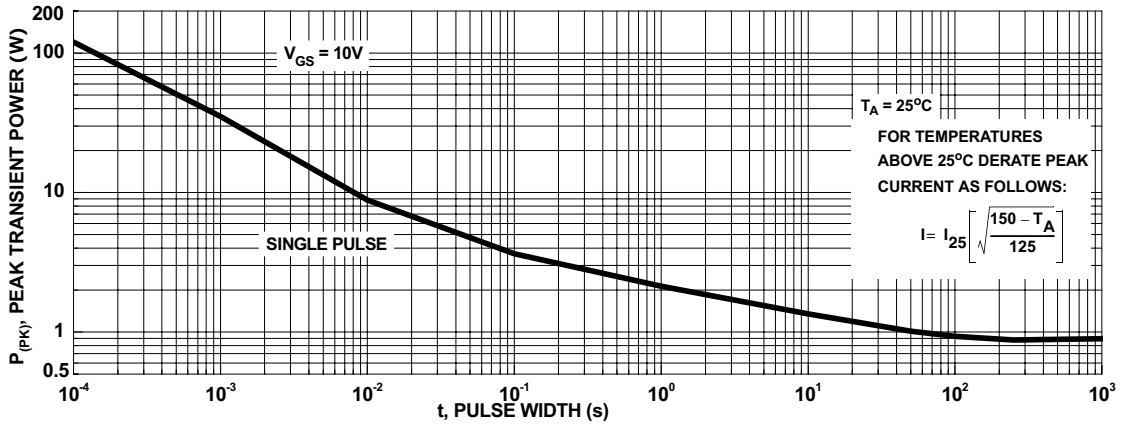


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

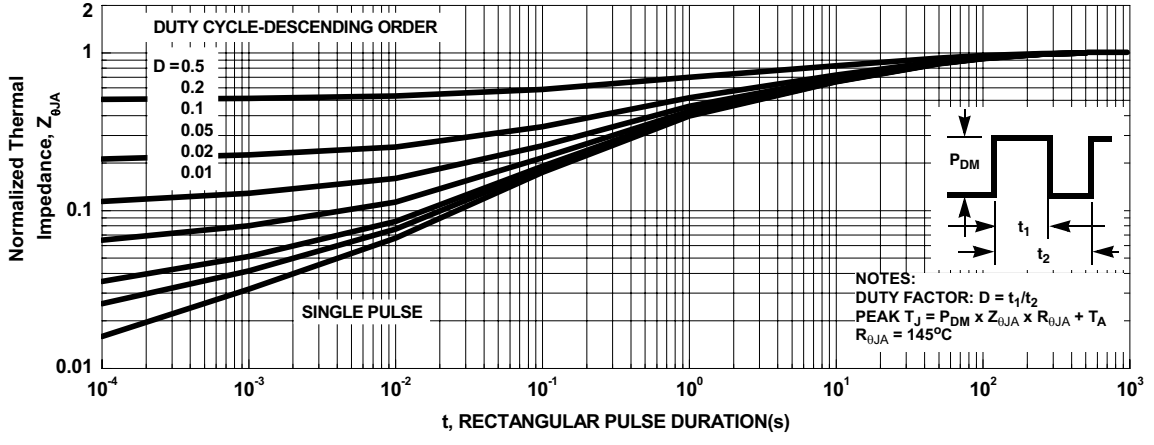
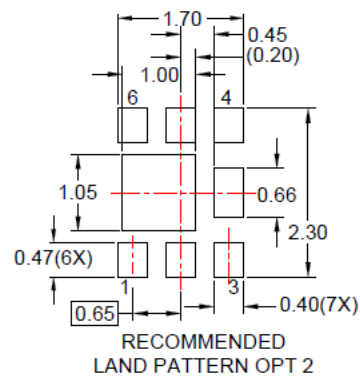
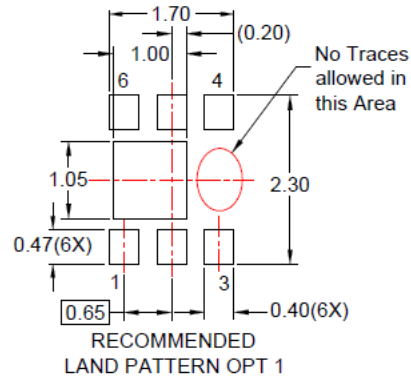
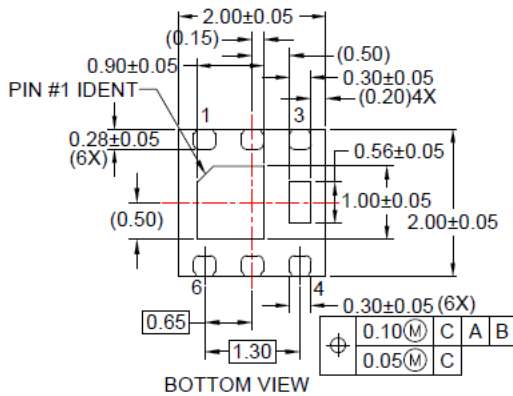
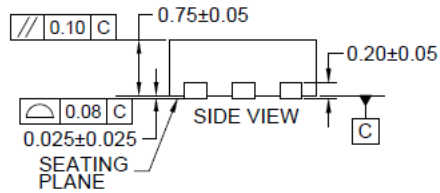
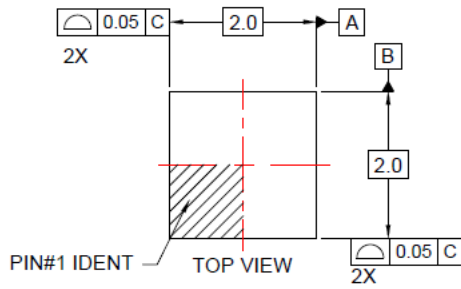


Figure 12. Transient Thermal Response Curve

Dimensional Outline and Pad Layout



NOTES:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC MO-229 REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP06Lrev4.







Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:
http://www.fairchildsemi.com/package/packageDetails.html?id=PN_MLDEB-C06



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|---|---|---|---|
| AccuPower™ | F-PFS™ |  | SYSTEM GENERAL® |
| AX-CAP®* | FRFET® | PowerTrench® | TinyBoost® |
| BitSiC™ | Global Power ResourceSM | PowerXS™ | TinyBuck® |
| Build it Now™ | GreenBridge™ | Programmable Active Droop™ | TinyCalc™ |
| CorePLUS™ | Green FPS™ | QFET® | TinyLogic® |
| CorePOWER™ | Green FPS™ e-Series™ | QST™ | TINYOPTO™ |
| CROSSVOL™ | Gmax™ | Quiet Series™ | TinyPower™ |
| CTL™ | GTO™ | RapidConfigure™ | TinyPWM™ |
| Current Transfer Logic™ | IntelliMAX™ |  | TinyWire™ |
| DEUXPEED® | ISOPLANAR™ | Saving our world, 1mW/W/kW at a time™ | TranSiC™ |
| Dual Cool™ | Marking Small Speakers Sound Louder and Better™ | SignalWise™ | TriFault Detect™ |
| EcoSPARK® | MegaBuck™ | SmartMax™ | TRUECURRENT®* |
| EfficientMax™ | MICROCOUPLER™ | SMART START™ | µSerDes™ |
| ESBC™ | MicroFET™ | Solutions for Your Success™ |  |
|  | MicroPak™ | SPM® | UHC® |
| Fairchild® | MicroPak2™ | STEALTH™ | Ultra FRFET™ |
| Fairchild Semiconductor® | MillerDrive™ | SuperFET® | UniFET™ |
| FACT Quiet Series™ | MotionMax™ | SuperSOT™-3 | VCX™ |
| FACT® | mWSaver® | SuperSOT™-6 | VisualMax™ |
| FAST® | OptoHiT™ | SuperSOT™-8 | VoltagePlus™ |
| FastvCore™ | OPTOLOGIC® | SupreMOS® | XS™ |
| FETBench™ | OPTOPLANAR® | SyncFET™ | 仙童™ |
| FPS™ | | Sync-Lock™ | |

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Fairchild Semiconductor:](#)

[FDMA430NZ](#)